

# MAGX-001090-600L00

# MAGX-001090-600L0S



**GaN on SiC HEMT Pulsed Power Transistor**  
**600 W Peak, 1030 to 1090 MHz, 32  $\mu$ s Pulse, 2% Duty**

Rev. V3

## Features

- GaN on SiC Depletion-Mode Transistor Technology
- Internally Matched
- Common-Source Configuration
- Broadband Class AB Operation
- RoHS\* Compliant and 260°C Reflow Compatible
- +50 V Typical Operation
- MTTF = 600 years ( $T_J < 200^\circ\text{C}$ )

## Applications

- Civilian Air Traffic Control (ATC), L-Band secondary radar for IFF and Mode-S avionics.
- Military radar for IFF and Data Links.

## Description

The MAGX-001090-600L00 is a gold metalized matched Gallium Nitride (GaN) on Silicon Carbide (SiC) RF power transistor optimized for pulsed avionics and radar applications. Using state of the art wafer fabrication processes, these high performance transistors provide high gain, efficiency, bandwidth, and ruggedness over a wide bandwidth for today's demanding application needs. High breakdown voltages allow for reliable and stable operation under more extreme mismatch load conditions compared with older semiconductor technologies.

## MAGX-001090-600L00



## MAGX-001090-600L0S



## Ordering Information

Part Number	Description
MAGX-001090-600L00	Flanged
MAGX-001090-600L0S	Flangeless
MAGX-001090-SB0PPR	1.03 - 1.09 GHz Evaluation Board

\* Restrictions on Hazardous Substances, European Union Directive 2002/95/EC.

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**Typical RF Performance under standard operating conditions,  $P_{OUT} = 600$  W (Peak)**

Freq (MHz)	$P_{IN}$ (W)	Gain (dB)	$I_D$ (A)	Eff. (%)	RL (dB)	Droop (dB)	+1dB OD (W)	VSWR-S (3:1)	VSWR-T (5:1)
1030	4.95	20.8	20.4	58.6	-16.8	0.24	649	S	P
1090	4.50	21.3	18.6	64.4	-11.0	0.23	661	S	P

**Electrical Specifications: Freq. = 1030 - 1090 MHz,  $T_A = 25^\circ\text{C}$**

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Units
<b>RF Functional Tests:</b>						
<b>Standard Pulse Conditions: <math>V_{DD} = 50</math> V, <math>I_{DQ} = 600</math> mA; Pulse = 32 <math>\mu</math>s / 2%</b>						
Input Power	$P_{OUT} = 600$ W Peak (12 W avg.)	$P_{IN}$	-	4.3	6.7	Wpk
Power Gain	$P_{OUT} = 600$ W Peak (12 W avg.)	$G_P$	19.5	21.4	-	dB
Drain Efficiency	$P_{OUT} = 600$ W Peak (12 W avg.)	$\eta_D$	55	63	-	%
Pulse Droop	$P_{OUT} = 600$ W Peak (12 W avg.)	Droop	-	0.2	0.3	dB
Load Mismatch Stability	$P_{OUT} = 600$ W Peak (12 W avg.)	VSWR-S	-	3:1	-	-
Load Mismatch Tolerance	$P_{OUT} = 600$ W Peak (12 W avg.)	VSWR-T	-	5:1	-	-
<b>Mode-S ELM Pulse Width Conditions<sup>1</sup>: <math>V_{DD} = 50</math> V, <math>I_{DQ} = 400</math> mA; 48 pulses of 32 <math>\mu</math>s on and 18 <math>\mu</math>s off, repeat every 24 ms; Overall Duty Factor = 6.4%</b>						
Input Power	$P_{OUT} = 550$ W Peak (35.2 W avg.)	$P_{IN}$	-	4.6	-	Wpk
Power Gain	$P_{OUT} = 550$ W Peak (35.2 W avg.)	$G_P$	-	20.7	-	dB
Drain Efficiency	$P_{OUT} = 550$ W Peak (35.2 W avg.)	$\eta_D$	-	61	-	%

1. For Mode-S ELM pulse conditions, RF power is measured at the middle of the 25th pulse in the burst ( $t \sim 1.216$  ms)

**Electrical Characteristics:  $T_A = 25^\circ\text{C}$**

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Units
<b>DC Characteristics:</b>						
Drain-Source Leakage Current	$V_{GS} = -8$ V, $V_{DS} = 175$ V	$I_{DS}$	-	1.0	30	mA
Gate Threshold Voltage	$V_{DS} = 5$ V, $I_D = 75$ mA	$V_{GS(TH)}$	-5	-3.1	-2	V
Forward Transconductance	$V_{DS} = 5$ V, $I_D = 17.5$ mA	$G_M$	12.5	19.2	-	S
<b>Dynamic Characteristics:</b>						
Input Capacitance	Not applicable - Input matched	$C_{ISS}$	N/A	N/A	N/A	pF
Output Capacitance	$V_{DS} = 50$ V, $V_{GS} = -8$ V, $F = 1$ MHz	$C_{OSS}$	-	55	-	pF
Reverse Transfer Capacitance	$V_{DS} = 50$ V, $V_{GS} = -8$ V, $F = 1$ MHz	$C_{RSS}$	-	5.5	-	pF

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## Absolute Maximum Ratings<sup>2,3,4,5</sup>

Parameter	Limit
Supply Voltage ( $V_{DD}$ )	+65 V
Supply Voltage ( $V_{GS}$ )	-8 to -2 V
Supply Current ( $I_{D(MAX)}$ )	82 A
Input Power ( $P_{IN}$ )	$P_{IN}$ (nominal) + 3 dB
Absolute Max. Junction/Channel Temp	200°C
Pulsed Power Dissipation at 85 °C	2.3 kW
Thermal Resistance, ( $T_J = 70$ °C) $V_{DD} = 50$ V, $I_{DQ} = 600$ mA, $P_{out} = 600$ W, 32 $\mu$ s Pulse / 2% Duty	0.05 °C/W
Operating Temp	-40 to +95°C
Storage Temp	-65 to +150°C
Mounting Temperature	See solder reflow profile
ESD Min. - Charged Device Model (CDM)	1300 V
ESD Min. - Human Body Model (HBM)	4000 V

2. Operation of this device above any one of these parameters may cause permanent damage.
3. Input Power Limit is +3 dB over nominal drive required to achieve  $P_{OUT} = 600$  W.
4. Channel temperature directly affects a device's MTTF. Channel temperature should be kept as low as possible to maximize lifetime.
5. For saturated performance it recommended that the sum of  $(3 \cdot V_{DD} + \text{abs}(V_{GS})) < 175$  V.

## Test Fixture Impedances

F (MHz)	$Z_{IF}$ ( $\Omega$ )	$Z_{OF}$ ( $\Omega$ )
1030	1.1 - j1.5	1.5 + j0.5
1060	1.1 - j1.4	1.5 + j0.6
1090	1.1 - j1.3	1.5 + j0.6

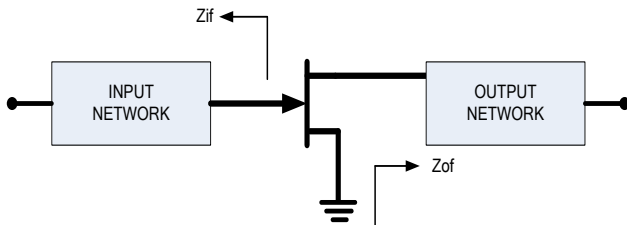
## Correct Device Sequencing

### Turning the device ON

1. Set  $V_{GS}$  to the pinch-off ( $V_P$ ), typically -5 V.
2. Turn on  $V_{DS}$  to nominal voltage (50 V).
3. Increase  $V_{GS}$  until the  $I_{DS}$  current is reached.
4. Apply RF power to desired level.

### Turning the device OFF

1. Turn the RF power off.
2. Decrease  $V_{GS}$  down to  $V_P$ .
3. Decrease  $V_{DS}$  down to 0 V.
4. Turn off  $V_{GS}$



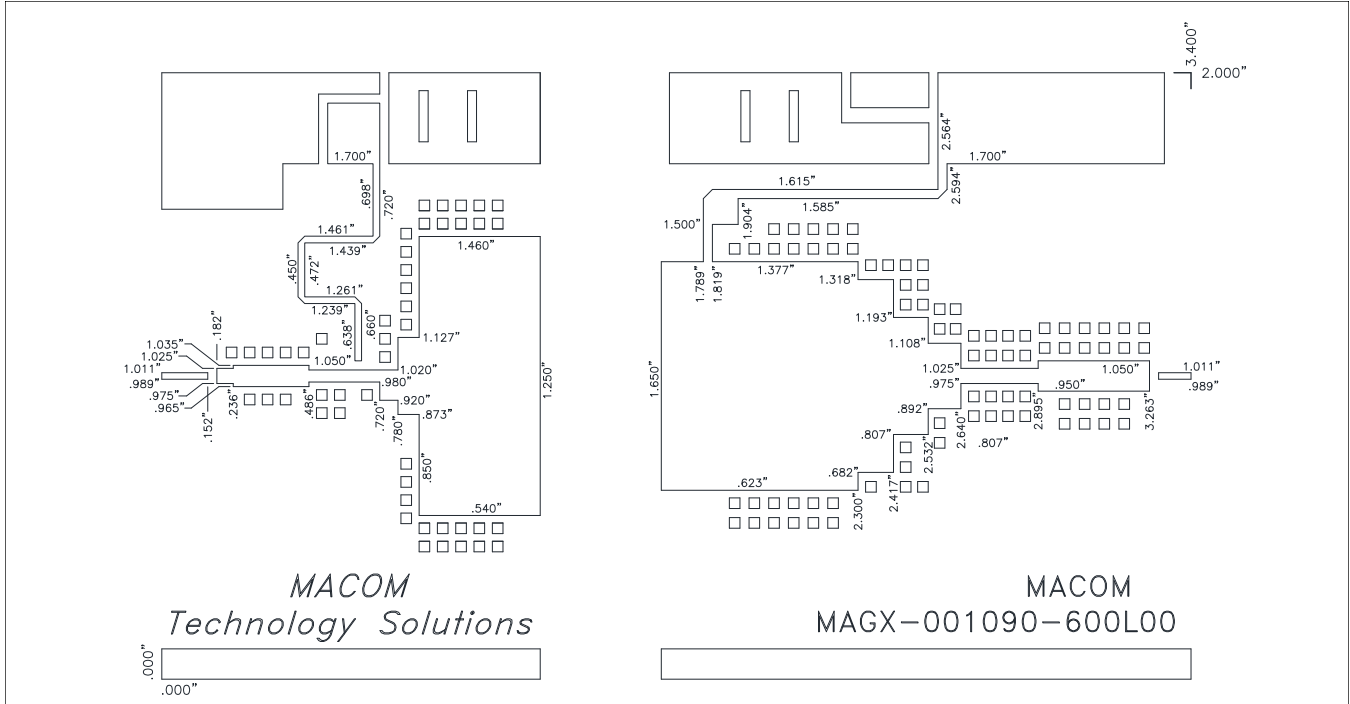
# MAGX-001090-600L00 MAGX-001090-600L0S



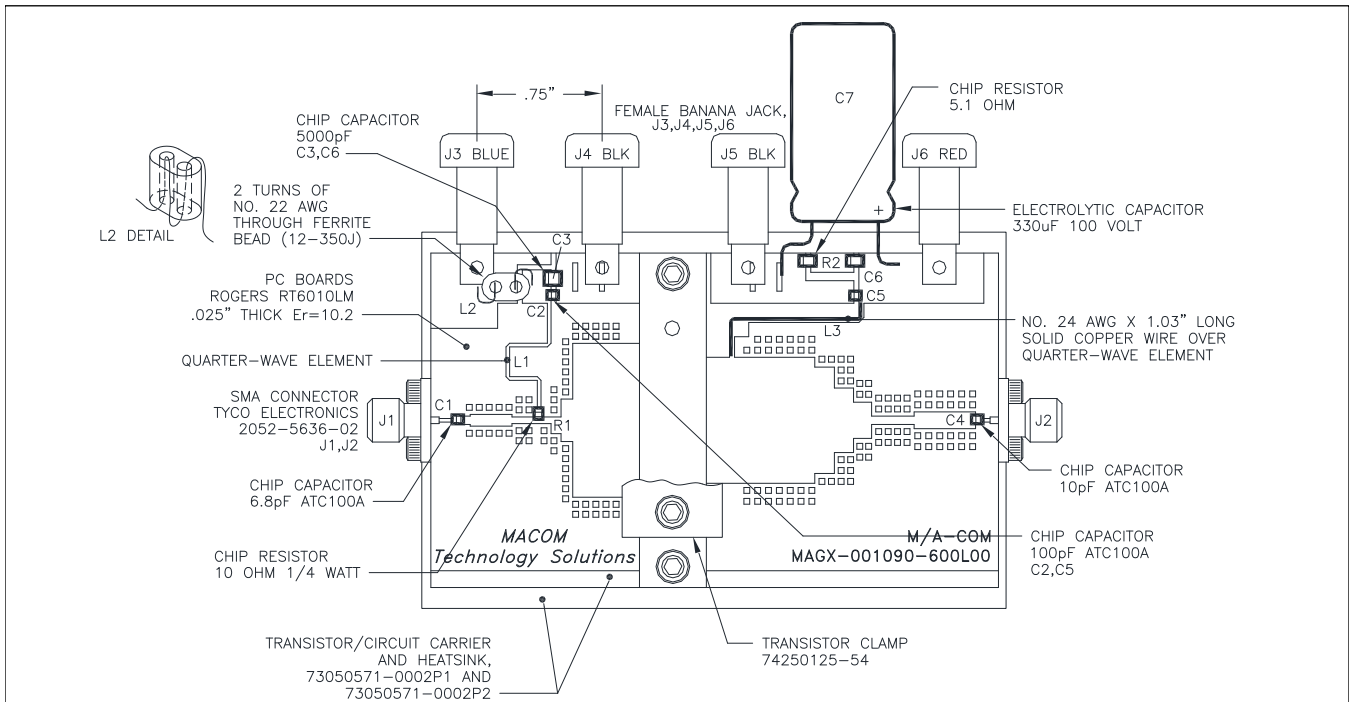
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## Test Fixture Circuit Dimensions

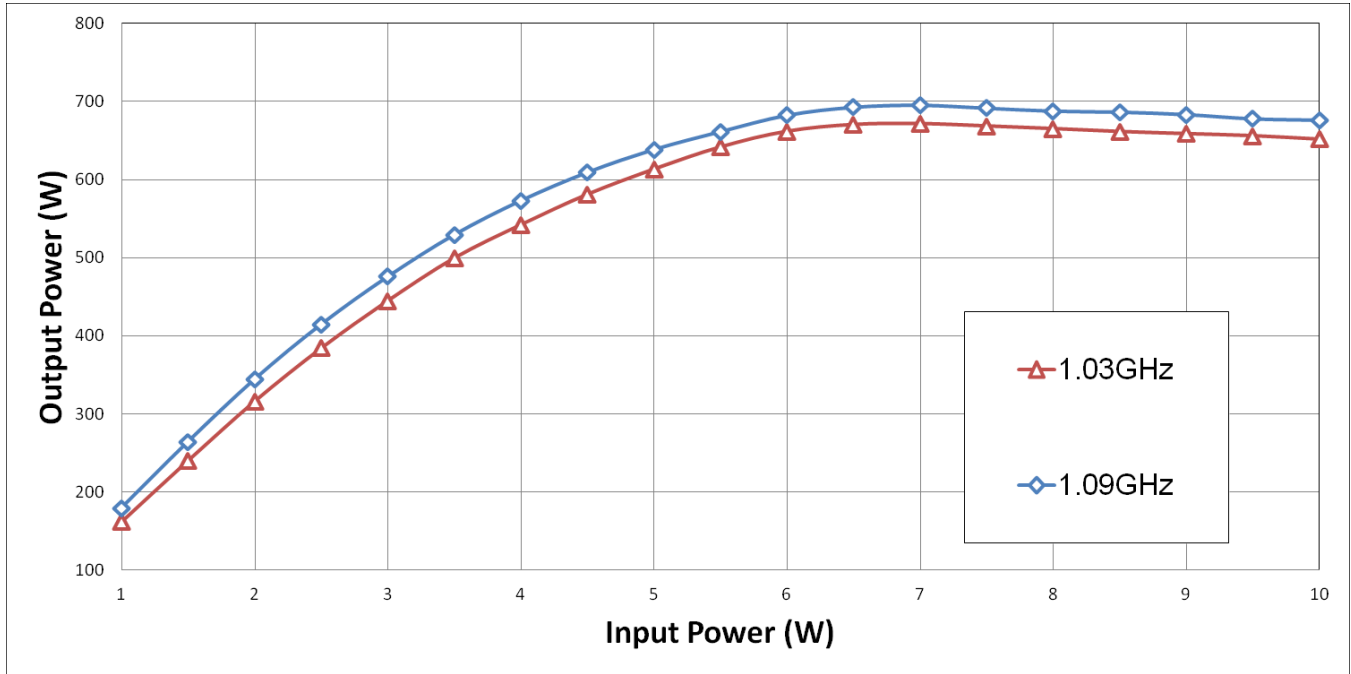


## Test Fixture Assembly

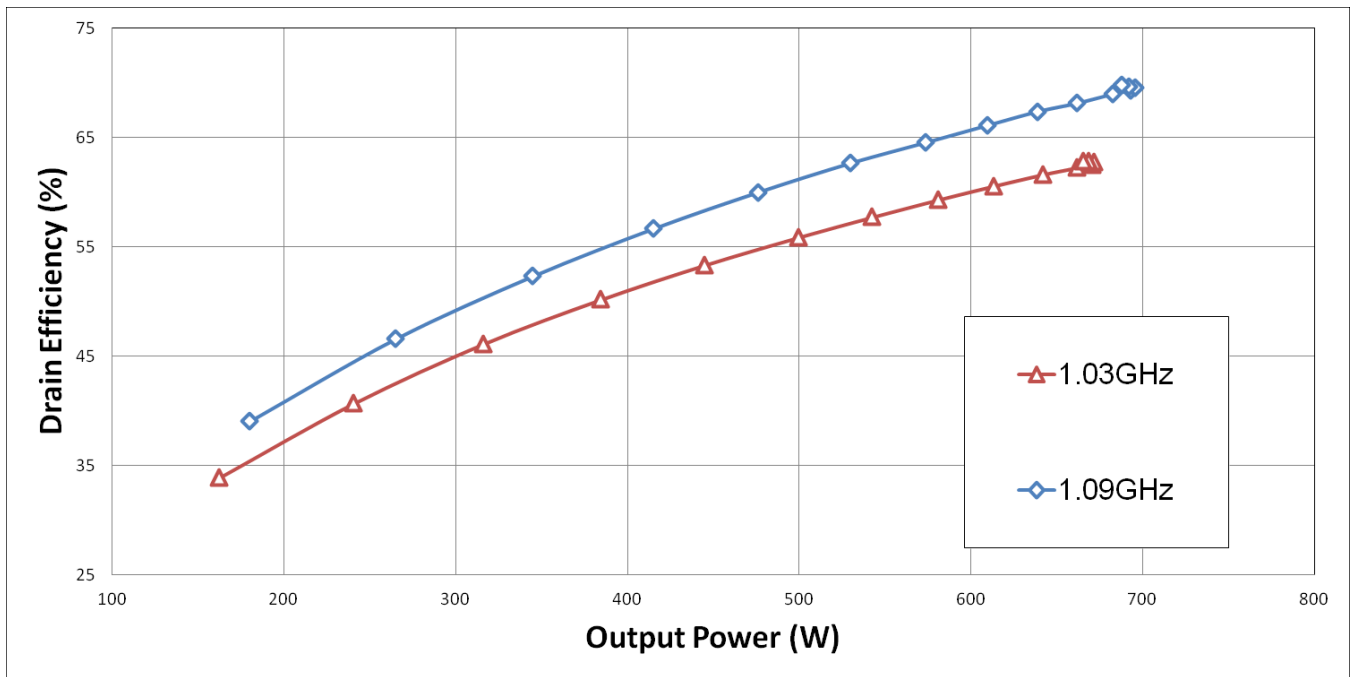


Contact factory for gerber file or additional circuit information.

**RF Power Transfer Curve (Output Power Vs. Input Power)**



**RF Power Transfer Curve (Drain Efficiency Vs. Output Power)**



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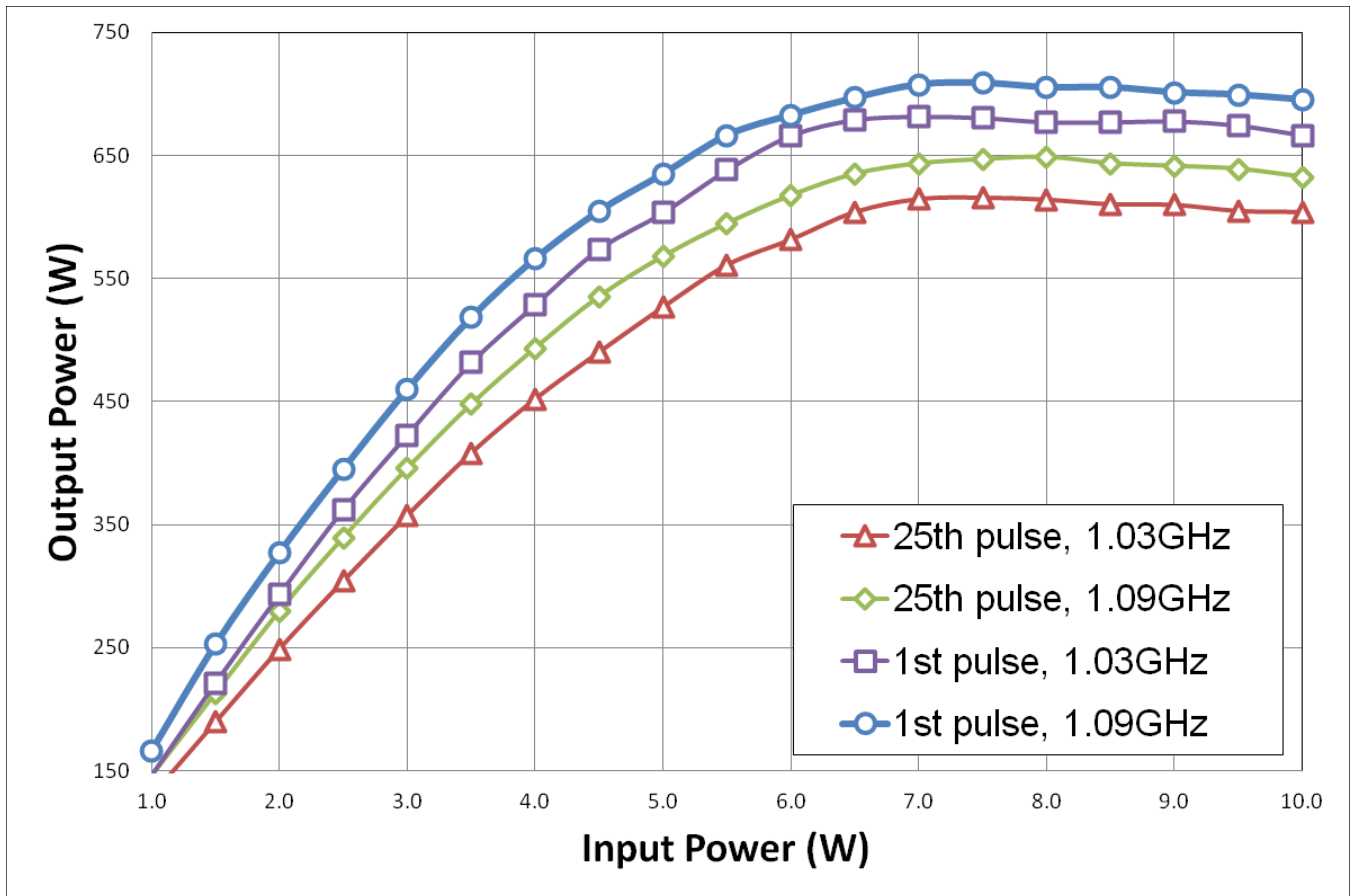
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Typical RF Data with Mode-S ELM 'pulse' conditions:

48 pulses of 32  $\mu$ s on and 18  $\mu$ s off, repeat every 24ms; Overall Duty Factor = 6.4%

$V_{DD} = 50$  V;  $I_{DQ} = 400$  mA



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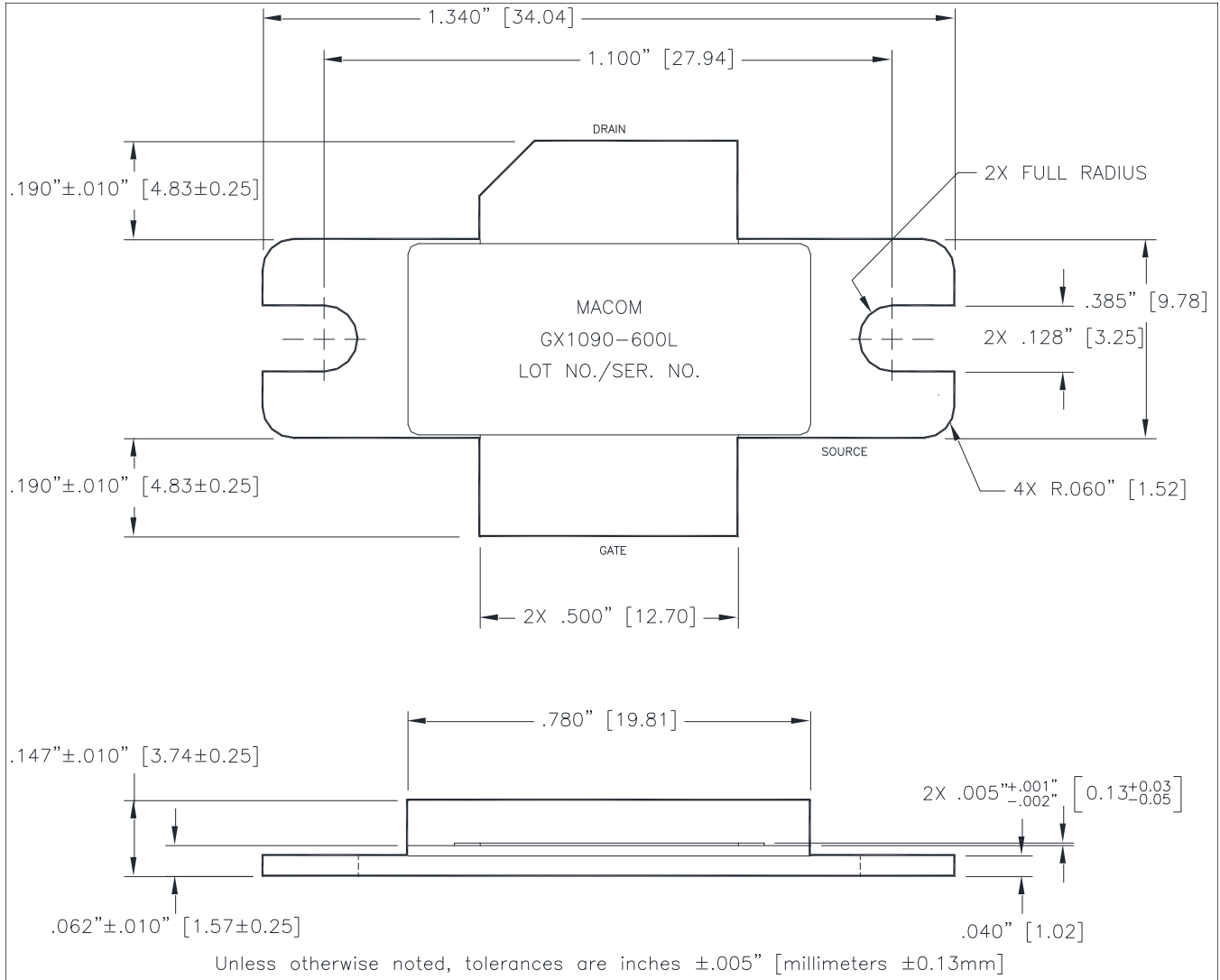
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### Outline Drawing MAGX-001090-600L00



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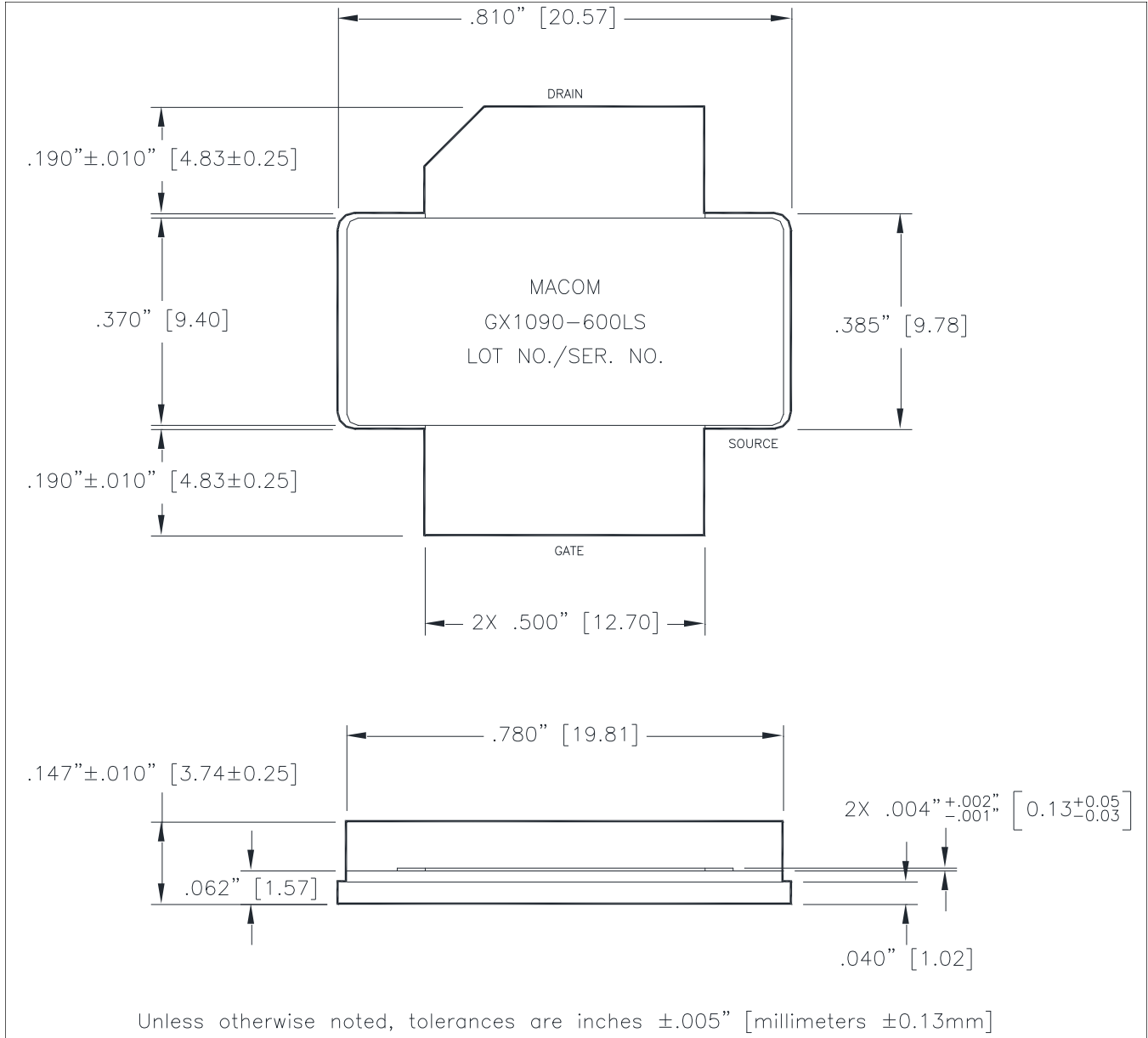
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